

Bill of Material

wearable-dev-kit

**Version:**

4

Date: 08.06.2016

Amount of pieces:

1

Currency:

EUR

Designator	Comment	Footprint	Remarks	Quantity	Manufacturer 1
+, Data	0906-1-15-20-75-14-11-0	PAD_SMD_1 mm_Rund		2	Mill-Max Manufacturing Corp.
C1, C4, C8, C9, C10, C22, C23, C24	100n	C_0402	16V/X7R	8	
C2, C3, C6, C12, C14	1u	C_0603	16V/X7R	5	
C5, C11	15p	C_0402	16V/X7R	2	
C7	10n	C_0402	16V/X7R	1	
C13	2u2	C_0603	16V/X7R	1	
C16	100n	C_0402	10V/X7R	1	
D1, D2	SP0502BXTG	SOT416-3L		2	Littelfuse Inc.
GND	0906-0-15-20-76-14-11-0	PAD_SMD_1 mm_Rund		1	Mill-Max Manufacturing Corp.
IC1	ATSAMD21G18A	QFN50P700 X700-48VAL		1	Atmel
IC2	MPU-9250	MPU-9250		1	InvenSense
IC3	MX25L12835FZNI	DFN127P600 X500x80-8		1	Macronix
IC4	MIC5235-1.8YM5	SOT23-5AL		1	Microchip Technology
IC5	AP7311-WG-7	SOT23-5AL		1	Diodes Incorporated
IC7	SHTC1	SHTC1		1	Sensirion
L1	BLM18PG221SN1D	L_0402		1	Murata Electronics North America
Q1	ABS07-32.768KHZ-T	2SMD-ABS07		1	Abracon LLC
R1	0R	R_0402	1%	1	
R2, R3, R4, R5, R6, R7, R8, R9, R10, R11, R15, R16	10k	R_0402	1%	12	
R12	68k	R_0402	0.1%	1	
R13	10k	R_0402	0.1%	1	
R14	100k	R_0402	1%	1	
S1					
ST3, ST4	FH33-4S-1SH(10)	1X4_1MM_H E_FH33-4S-1SH(10)		2	Hirose Electric Co Ltd
T1, T2, T3, T4	RUE002N02TL	SOT416-3L		4	Rohm Semiconductor
USB1	MICRO USB 2.0 B	USB MICRO 2.0 B SMT JAE- Electronics		1	JAE Electronics